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Kingbright SC05-11SYKWA

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12.7mm (0.5INCH) SINGLE DIGIT NUMERIC DISPLAY

The Super Bright Yellow device is made with AlGaInP (on

Part Number: SC05-11SYKWA

Description

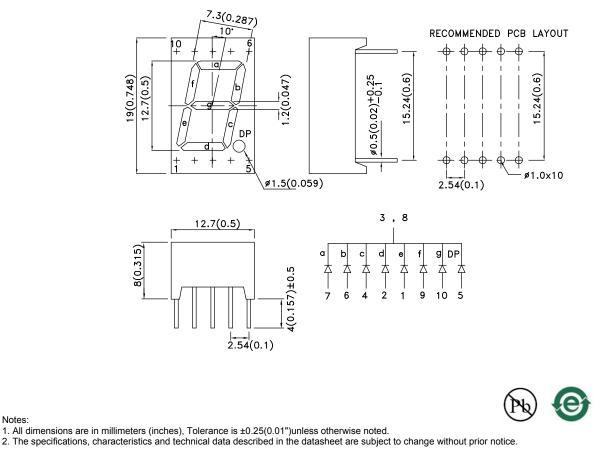
Super Bright Yellow

GaAs substrate) light emitting diode chip.

Features

- 0.5 inch digit height.
- Low current operation.
- Excellent character appearance.
- Easy mounting on P.C. boards or sockets.
- Mechanically rugged.
- Standard : gray face, white segment.
- · RoHS compliant.

Package Dimensions& Internal Circuit Diagram



Notes:



Selection Guide

Part No.	Dice	Lens Type	lv (ucd) [1] @ 10mA		Description		
			Min.	Тур.			
SC05-11SYKWA	Super Bright Yellow (AlGaInP)	White Diffused	52000	120000	Lommon Cathode, Rt. Hand Decimal		
			*21000	*40000			

Note:

1. Luminous intensity/ luminous Flux: +/-15%.

*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Yellow	590		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	20		nm	I⊧=20mA
С	Capacitance	Super Bright Yellow	20		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Super Bright Yellow	2.0	2.5	V	I⊧=20mA
IR	Reverse Current	Super Bright Yellow		10	uA	VR=5V

Notes:

1.Wavelength: +/-1nm.

2.Forward Voltage: +/-0.1V.

3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ParameterSuper Bright YellowPower dissipation75DC Forward Current30Peak Forward Current [1]175Reverse Voltage5

Absolute Maximum Ratings at TA=25°C

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

Operating / Storage Temperature

2. 2mm below package base.

Lead Solder Temperature[2]

-40°C To +85°C

260°C For 3-5 Seconds

Units

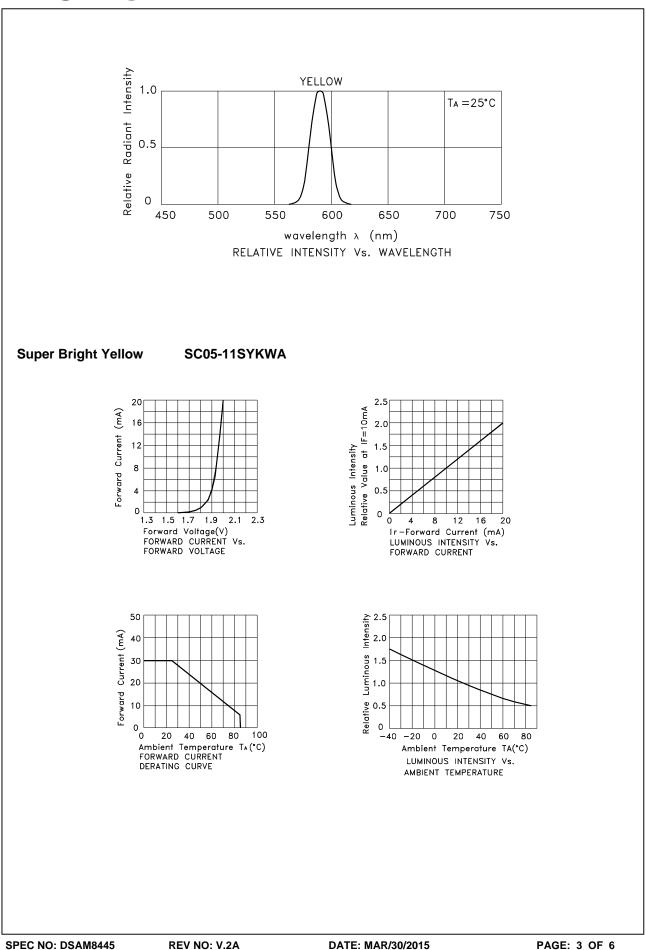
mW

mΑ

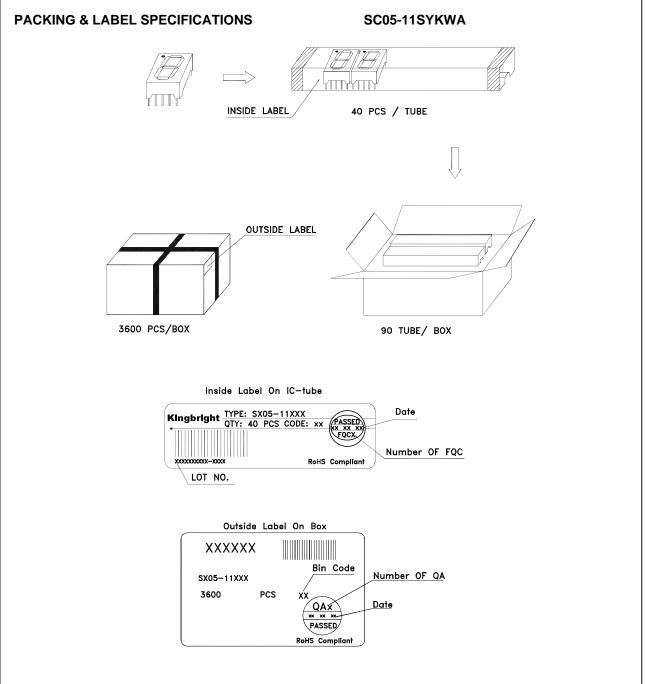
mΑ

v







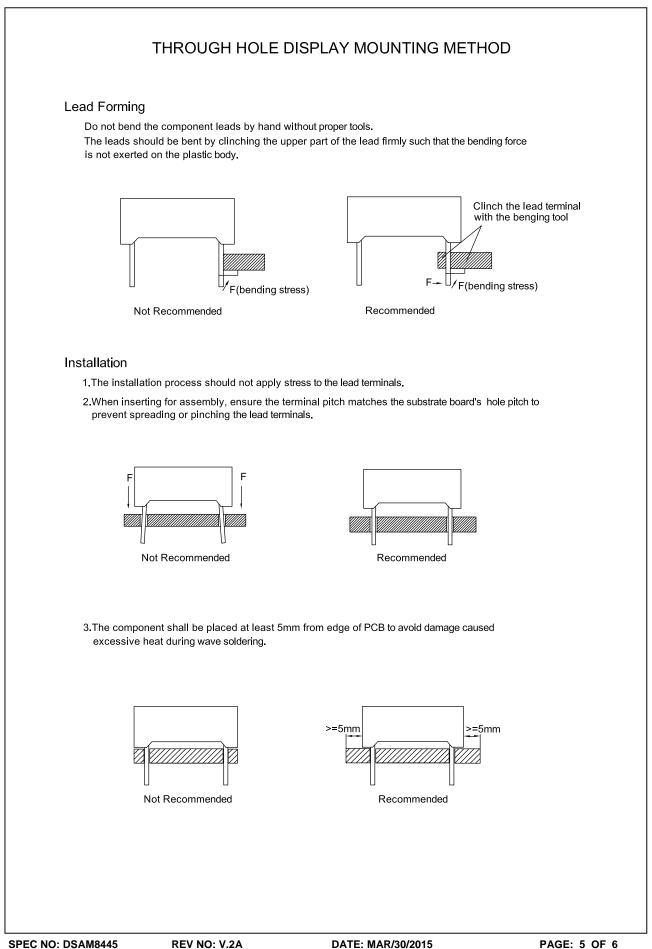


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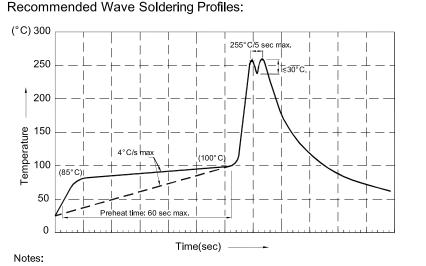
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SPEC NO: DSAM8445	REV NO: V.2A	DATE: MAR/30/2015	PAGE: 4 OF 6









 Recommend pre-heat temperature of 105° C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260° C

- 2.Peak wave soldering temperature between 245° C ~ 255° C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.

4. Fixtures should not incur stress on the component when mounting and during soldering process.

- 5.SAC 305 solder alloy is recommended.
- 6 No more than one wave soldering pass.
- 7.During wave soldering, the PCB top-surface temperature should be kept below 105°C.

Soldering General Notes:

1. Through-hole displays are incompatible with reflow soldering.

2.If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

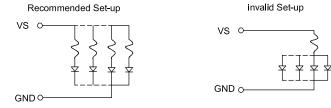
1.Mild "no-clean" fluxes are recommended for use in soldering.

- 2. If cleaning is required, Kingbright recommends to wash components with water only.
 - Do not use harsh organic solvents for cleaning because they may damage the plastic parts .
- 3.The cleaning process should take place at room temperature and the devices should not be washed for more than one minute.
- 4. When water is used in the cleaning process, immediately remove excess moisture from the component with forced-air drying afterwards.

CIRCUIT DESIGN NOTES

1.Protective current-limiting resistors may be necessary to operate the LEDs within the specified range.

2.LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.



- 3. The driving circuit should be designed to protect the LED against reverse voltages and transient voltage spikes when the circuit is powered up or shut down.
- 4. The safe operating current should be chosen after considering the maximum ambient temperature of the operating environment.
- 5. Prolonged reverse bias should be avoided, as it could cause metal migration, leading to an increase in leakage current or causing a short circuit.